



PRODUCT DATASHEET



DC Input Photo Coupler

DIP6 Gullwing 400mil
Random-Phase <u>TRIAC</u>

TD301X(M)-GV





APPLICATIONS:

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

TD301X(M) Series

DESCRIPTION:



The TD301X(M) series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo TRIAC in a plastic DIP6 package with Gullwing lead forming option.

With the robust coplanar double mold structure, TD301X(M) series provide the most stable isolation feature.

FEATURES:

- High isolation 5000Vrms
- DC input with random-phase photo TRIAC output
- Operating temperature range -40°C to +100°C
- REACH & RoHS compliance
- MSL class 1
- Regulatory Approvals:
 - o UL UL1577
 - VDE EN60747-5-5 (VDE0884-5)
 - o CQC GB4943.1, GB8898
- cUL CSA Component Acceptance Service Notice 5A
- Packing: 65pcs/tube



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NAMING & ORDERING INFORMATION:

Naming Information:

TD301 X (M) - G V				
TD301X	Part Number			
×	Selection: LED Trigger Current (X=0~2)			
Μ	Lead Form Option: DIP6 Gullwing			
G	Green Option			
V	VDE Option			

Ordering Information:

TD301 <mark>ێ(</mark> M)-GV						
\underline{X} = Selection: LED Trigger Current (X=0~2)						
Part Number	Symbol	Values			Unit	Test Condition
		Min.	Тур.	Max.	Onic	rest condition
TD3010(M)-GV				15		L =100m A
TD3011(M)-GV	I _{FT}			10	mA	Terminal
TD3012(M)-GV				5		voltage=3V

Version No.	Original Release Date
Rev: A00	05/09/2024



SCHEMATIC DIAGRAM & MARKING:

Schematic Diagram: **PIN Definition** 1 Anode 1 2 Cathode NC 2 3 4 Terminal 3 5 Substrate 6 Terminal

Marking Information:



Labelling Information:





Absolute Maximum Ratings:

Parameter	Symbol	Ratings	Unit			
INPUT						
Forward Current	IF	60	mA			
Reverse Voltage	V _R	6	V			
Junction Temperature	Tj	125	°C			
Input Power Dissipation	Pı	100	mW			
(OUTPUT					
Off-State Output Terminal Voltage	Vdrm	250	V			
Peak Repetitive Surge Current PW=100μs, 120pps	Ітям	1	А			
On-State RMS Current	I _{T(RMS)}	100	mA			
Junction Temperature	Tj	125	°C			
Output Power Dissipation	Po	300	mW			
COMMON						
Total Power Dissipation	P _{tot}	400	mW			
Isolation Voltage	Viso	5000 ^{*1}	Vrms			
Operating Temperature	T _{opr}	-40~+100	°C			
Storage Temperature	Tstg	-55~+125	°C			
Soldering Temperature	T _{sol}	260 *2	°C			

*1. AC for 1 minute, R.H.=40~60%.

*2. For 10 seconds max.



ELECTRICAL CHARACTERISTICS:

Parameter		Symbol	Values			Unit	Tast Condition
		Symbol	Min.	Тур.	Max.	Unit	Test Condition
	INPUT						
Forward Voltage		V _F		1.24	1.4	V	I _F =10mA
Reverse Current		I _R			10	μA	V _R =6V
Input Capacitance		Cin		8.5	250	pF	V=0, f=1kHz
			OUTPL	JT			
Peak Off-State Currer Either Direction	nt	Idrm			100 *1	nA	V _{DRM} =Rated V _{DRM} I _F =0
Peak On-State Voltag Either Direction	je	V _{TM}		1.58	2.5	V	I _{TM} =100mA
Critical Rate of Rise o Voltage	f Off-State	dV/dt	1000			V/µs	V _{PEAK} =400V I _F =0
TRANSFER CHARACTERISTICS							
LED Trigger Current	TD3010				15		-100mA
	TD3011	IFT			10	mA	Terminal Voltage=3V
	TD3012				5		
Holding Current		Ін		257		μΑ	
Isolation Resistance		R _{ISO}	10^12	10^14		Ω	DC=500V, 40~60% R.H.
Floating Capacitance		Сю		0.8		pF	V=0, f=1MHz

*1. Test voltage must be applied within dV/dt rating.



CHARACTERISTIC CURVES:









CHARACTERISTIC CURVES:









TEST CIRCUIT:



Test Circuit and Waveforms of Turn On Time:

Test Circuit and Waveforms of dV/dt:





OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).



PACKING SPECIFICATION:

Tube Dimension:





RECOMMENDED SOLDERING PROFILE:

Reflow Information:

Γ

Supplier T _p ≥	T _c Us T _c -5°C	er $T_p \leq T_c$ User t_p
Tp Max. R Max. R	amp Up Rate = 3°C/s amp Down Rate = 6°C/s t	t _p -+, T _c -5°C
Profile Feature	Sn Dh Assambly Profile	PC-0201-
Temperature Min (Temin)		
Temperature Max (T)	150°C	200°C
Time (t.) from (Terris to Terris)	60-120 seconds	60-120 seconds
Ramp-un Rate (ti to to)	3°C/second max	3°C/second may
	183°C	217°C
Time (t ₁) Maintained Above (T ₁)	60-150 seconds	60-150 seconds
Peak Rody Package Temperature	235°C ±0°C / _5°C	260°C ±0°C / -5°C
Time (t_0) within 5°C of 260°C	200 seconds	30 seconds
Pamp down Pato /T- to T-	6°C/cocond may	SU SECULIUS
Ramp-uown Rate (TP to TL)	o Crseconu max.	o cyseconu max.



RECOMMENDED SOLDERING PROFILE:

Wave Soldering (JESD22-A111 Compliant):



Hand Soldering:

Soldering Temperature	380±5°C
Soldering Time	3 sec max.

Note:

- One time soldering is recommended for all soldering methods.
- Do not solder more than three times for IR reflow soldering.